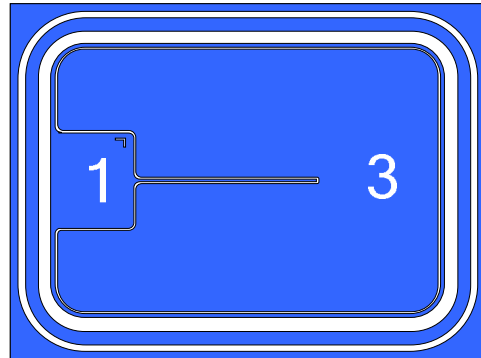


3VD235700YL HIGH VOLTAGE MOSFET CHIPS

DESCRIPTION

- 3VD235700YL is a High voltage N-Channel enhancement mode power MOS-FET chip fabricated in advanced silicon epitaxial planar technology.
- Advanced termination scheme to provide enhanced voltage-blocking capability.
- Avalanche Energy Specified
- Source-to-Drain Diode Recovery Time Comparable to a Discrete Fast Recovery Diode
- The chips may packaged in TO-251 type and the typical equivalent product is 2N70.
- The packaged product is widely used in AC-DC power suppliers, DC-DC converters and H-bridge PWM motor drivers.



1-Gate PAD 3-Source PAD

CHIP TOPOGRAPHY

CHIP INFORMATION

Item	Characterization
Wafer Size	6Inch
Die Size	2060 μ m *2720 μ m
Gross Die Per Wafer	2815 dice/wafer
Wafer Thickness	300 \pm 20 μ m.
Top Metal /Thickness	Al(1%Si): 3 μ m
Back Metal /Thickness	Ti/Ni/Ag:0.1/0.3/0.4 μ m
Gate PAD size(PAD1)	454.2 μ m *536 μ m
Scribe line Width	80 μ m *80 μ m

ABSOLUTE MAXIMUM RATINGS (T_{amb}=25°C)

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	V _{DS}	700	V
Gate-Source Voltage	V _{GS}	\pm 30	V
Drain Current	I _D	2.0	A
Power Dissipation (TO-251 Package)	P _D	44	W
Operation Junction Temperature	T _J	150	°C
Storage Temperature	T _{stg}	-55~+150	°C

ELECTRICAL CHARACTERISTICS (T_{amb}=25°C)

Parameter	Symbol	Test conditions	Min.	Typ.	Max.	Unit
Drain -Source Breakdown Voltage	BVDSS	V _{GS} =0V, I _D =250μA	700	-	-	V
Gate Threshold Voltage	V _{TH}	V _{GS} = V _{DS} , I _D =250μA	2.0	-	4.0	V
Drain-Source Leakage Current	I _{DSS}	V _{DS} =700V, V _{GS} =0V	-	-	1.0	μA
Static Drain- Source On State Resistance	R _{DS(on)}	V _{GS} =10V, I _D =1.0A	-	-	6.5	Ω
Gate-Source Leakage Current	I _{GSS}	V _{GS} =±30V, V _{DS} =0V	-	-	±100	nA
Source-Drain Diode Forward on Voltage	V _{FSD}	I _S =2.0A, V _{GS} =0V	-	-	1.4	V

Disclaimer :

- Silan reserves the right to make changes to the information herein for the improvement of the design and performance without further notice! Customers should obtain the latest relevant information before placing orders and should verify that such information is complete and current.
- All semiconductor products malfunction or fail with some probability under special conditions. When using Silan products in system design or complete machine manufacturing, it is the responsibility of the buyer to comply with the safety standards strictly and take essential measures to avoid situations in which a malfunction or failure of such Silan products could cause loss of body injury or damage to property.
- Silan will supply the best possible product for customers!